DECLARATION FOR U.S. PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

MASTER BATCH CONTAINING HEAT RADIATION SHIELDING COMPONENT, AND
HEAT RADIATION SHIELDING TRANSPARENT RESIN FORM AND HEAT RADIATION
SHIELDING TRANSPARENT LAMINATE FOR WHICH THE MASTER BATCH HAS BEEN USED

the specificati	on of which is attached hereto ur	aless the following is ch	ecked	
	on as United States Applicated on (if applicable).	ation Number or	PCT International Application	on Number
	that I have reviewed and underst nended by any amendment refer		above-identified specification	, including the
I acknowledge Federal Regul	the duty to disclose information ations, § 1.56.	which is material to pa	tentability as defined in Title	37, Code of
application(s) patent or inver	foreign priority benefits under? for patent or inventor's certificat ntor's certificate having a filing o	e listed below and have	also identified below any for	eign application for
(List prior foreign applications, See noue A below) (See note B beli		73.03.03	21/07/2002	Пи Пи
	(Number)	JAPAN (Country)	31/07/2002 (Day/Month/Year Filed)	Yes □ No
	(transcr)	(Country)	(Daynanda real riled)	*
				Yes No
	(Number)	(Country)	(Day/Month/Year Filed)	
	- Ol-t-	(Country)	10. At 12. A	Yes No
	(Number)	(Country)	(Day/Month/Year Filed)	
				☐ Yes ☐ No
	(Number)	(Country)	(Day/Month/Year Filed)	
		ed list for additional pri		
and, insofar a application in duty to disclos	n the benefit under Title 35, Ur s the subject matter of each of the manner provided by the fir se information which is material secame available between the fil his application.	the claims of this appli st paragraph of Title 3: I to patentability as def	cation is not disclosed in the 5, United States Code, § 11 ined in Title 37, Code of F	e prior United States 2, I acknowledge the ederal Regulations, §
			Stat	us
(List prior U.S. Applications)			☐ Patented ☐ Pending ☐ Abandoned	
	(Application Serial No.)	(Filing Date)		ling [_] Abandoned
	(Application Serial No.)	(Filing Date)	Patented Pend	ling Abandoned
	(Application Serial No.)	(Filing Date)	Patented Pend	ling Abandoned

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:



Please direct all communications to the following address:

(See note C)



I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18 of the United States Code, § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Kenichi FUJITA

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Full name of fourth inventor (given name, family name)				
Inventor's signature	Date			
Residence	Citizenship			
Post Office Address				
Full name of fifth inventor (given name, family name)				
Inventor's signature	Date			
Residence	Citizenship			
Post Office Address				